

Zaliman Sauli

List of Publications by Year in descending order

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44
times ranked

40
citing authors

#	ARTICLE	IF	CITATIONS
1	Reliability comparison between solder and solderless flip chip interconnection in terms of high temperature storage. AIP Conference Proceedings, 2020, , .	0.3	0
2	A Brief Review on Breast Carcinoma and Deliberation on Current Non Invasive Imaging Techniques for Detection. Current Medical Imaging, 2019, 15, 85-121.	0.4	7
3	A review on the Skyrme Hartree-Fock model and related topics. AIP Conference Proceedings, 2017, , .	0.3	0
4	A review: Application of adhesive bonding on semiconductor interconnection joints. AIP Conference Proceedings, 2017, , .	0.3	6
5	A review on solder reflow and flux application for flip chip. AIP Conference Proceedings, 2017, , .	0.3	3
6	A short review on thermosonic flip chip bonding. AIP Conference Proceedings, 2017, , .	0.3	3
7	Finite element modelling of thermal performance of LED lamp using open source software - salome and elmer. , 2017, , .		2
8	Teardrop shaped breast surface change assessment via digital fringe projection. , 2017, , .		0
9	A crunch on thermocompression flip chip bonding. AIP Conference Proceedings, 2017, , .	0.3	0
10	Symmetry Energy and Surface Clustering in Nuclei; Probing the Asymmetric Nuclear Matter. , 2015, , .		0
11	Convection Condition Variation Analysis on Thermal Dissipation of High Power Single Chip LED. Advanced Materials Research, 2014, 1082, 336-339.	0.3	0
12	Heat Sink Cooling Fan and Rotation Speed Effect Analysis on Heat Dissipation of High Power GaN LED Package. Advanced Materials Research, 2014, 1082, 315-318.	0.3	0
13	Metallic Layer Reflectance Analysis Using Design of Experiment. Advanced Materials Research, 2014, 893, 461-464.	0.3	0
14	CuDia Slug Size Variation Analysis on Heat Dissipation of High Power LED. Applied Mechanics and Materials, 2014, 487, 33-36.	0.2	2
15	Surface Roughness Scrutinization with RIE CF ₄ +Argon Gaseous on Platinum Deposited Wafer. Applied Mechanics and Materials, 2014, 487, 71-74.	0.2	0
16	LED Heat Dissipation Analysis Using Composite Based Cylindrical Slug. Advanced Materials Research, 2014, 893, 803-806.	0.3	1
17	Natural Heat Convection Analysis on Cylindrical Al Slug of LED. Applied Mechanics and Materials, 2014, 487, 536-539.	0.2	3
18	Shear Ram Speed Analysis for Gold Wire Bond Shear Test. , 2013, , .		0

#	ARTICLE	IF	CITATIONS
19	Finite Element Analysis on Sn-3.9Ag-0.6Cu and Sn-3.5Ag-0.7Cu Using Different Shearing Height. , 2013, , .		0
20	Stress Analysis on Through Holes in PCB. , 2012, , .		6
21	Gold and Copper Ball Bond Shear Stress Comparison At Different Shear Tool Heights. , 2012, , .		3
22	Shear Stress Analysis Study Using Surface Morphology Correlation with Aluminium Ball Adhesion. , 2012, , .		10
23	Polymer Core BGA Vertical Stress Loading Analysis. , 2012, , .		5
24	Shearing Speed Induced Stress Comparison on Gold and Copper Ball Interconnection. , 2012, , .		9
25	Interaction of Surface Roughness and Copper Ball Adhesion Using Shearing Simulation. , 2012, , .		11
26	Gold Ball Shear Stress Analysis on Different Surface Morphology. , 2012, , .		6
27	CORE NUCLEUS DYNAMICS IN \hat{I} HYPERNUCLEI. International Journal of Modern Physics E, 2009, 18, 1302-1312.	0.4	1
28	Electrode design and planar uniformity of anodically etched small area porous silicon. , 2009, , .		0
29	5mm \hat{A} – 5mm Sized Slug on High Power LED Stress and Junction Temperature Analysis. Applied Mechanics and Materials, 0, 404, 460-464.	0.2	0
30	Bump Height at Low Temperature Analysis. Applied Mechanics and Materials, 0, 404, 77-81.	0.2	0
31	Shear Speed Analysis on Sn-3.9Ag-0.6Cu Solder. Applied Mechanics and Materials, 0, 404, 72-76.	0.2	0
32	Aluminium Surface Grain Size Analysis on RIE Treatment. Applied Mechanics and Materials, 0, 404, 67-71.	0.2	2
33	Heat Slug Material Variation Analysis on Thermal Dissipation of High Power LED. Advanced Materials Research, 0, 1082, 319-322.	0.3	0
34	Effect of High Temperature during Electroless Nickel Process. Advanced Materials Research, 0, 925, 88-91.	0.3	0
35	Heat Sink Fin Number Variation Analysis on Single Chip High Power LED. Applied Mechanics and Materials, 0, 487, 149-152.	0.2	2
36	Main Effects Study on Plasma Etched Aluminium Metallization. Applied Mechanics and Materials, 0, 487, 195-198.	0.2	0

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37	Grain Size Analysis on $\text{Ba}_{0.65}\text{Sr}_{0.35}\text{TiO}_3$ Thin Films Using Design of Experiment. <i>Advanced Materials Research</i> , 0, 896, 211-214.	0.3	2
38	Chemical Bath Temperature Investigation for Electroless Nickel Immersion Gold. <i>Advanced Materials Research</i> , 0, 925, 96-100.	0.3	0
39	Quantitative Bump Height Analysis in ENIG Using Design of Experiment. <i>Advanced Materials Research</i> , 0, 896, 660-663.	0.3	0
40	Surface Roughness Analysis on Reactive Ion Etched Aluminium Deposited Wafer. <i>Applied Mechanics and Materials</i> , 0, 487, 141-144.	0.2	0
41	Operating Temperature Analysis of LED with Cylindrical Cu Slug. <i>Applied Mechanics and Materials</i> , 0, 487, 145-148.	0.2	2
42	Analysis on Surface Roughness and Surface Reflectance through DOE. <i>Applied Mechanics and Materials</i> , 0, 487, 37-40.	0.2	0
43	Copper Based Heat Slug Structure Variation Analysis on Heat Dissipation of High Power LED. <i>Advanced Materials Research</i> , 0, 1082, 340-343.	0.3	0
44	Heat Dissipation Simulation Analysis of High Power LED via Heat Slug Geometry Variation. <i>Advanced Materials Research</i> , 0, 1082, 344-347.	0.3	0